

# Switch, N-Chanel MMBF4093

## **Features**

- This Device is Designed for Low Level Analog Switching Applications, Sample and Hold Circuits and Chopper Stabilized Amplifiers.
- Sourced from Process 51.
- This is a Pb-Free and a Halide Free Device

## ABSOLUTE MAXIMUM RATINGS (Note 1), (Note 2)

(T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DG}$	Drain-Gate Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	-40	V
I <sub>GF</sub>	I <sub>GF</sub> Forward Gate Current		mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to + 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. These ratings are based on a maximum junction temperature of 150°C.
- These are steady-state limits. onsemi should be consulted on applications involving pulsed or low-duty cycle operations.

THERMAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Characteristic	Max	Unit	
$P_{D}$	Total Device Dissipation	350	mW	
	Derate above 25°C	2.8	mW/°C	
R <sub>θ</sub> JA	Thermal Resistance, Junction to Ambient (Note 3)	357	°C/W	

3. Device mounted on FR-4 PCB 1.6"  $\times$  1.6"  $\times$  0.06".



SOT-23 CASE 318-08

Note: Source & Drain are interchangeable

## MARKING DIAGRAM



61L = Specific Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBF4093	SOT-23 (Pb-Free)	3000 / Tape and Real

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## MMBF4093

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Max	Unit
FF CHARAC	TERISTICS	•	-	-	•
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	-40	_	V	
V <sub>GS</sub> (off)	Gate-Source Cut-Off Voltage	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 1 nA	-1.0	-5.0	V
I <sub>DGO</sub>	Drain–Gate Leakage Current $ \begin{aligned} V_{DG} &= 20 \text{ V, I}_S = 0 \\ V_{DG} &= 20 \text{ V, I}_S = 0, T_A = 150 ^{\circ}\text{C} \end{aligned} $		- -	-200 -400	pA nA
I <sub>D</sub> (off)	Drain Cutoff Leakage Current	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = -6 V V <sub>DS</sub> = 20 V, V <sub>GS</sub> = -6 V, T <sub>A</sub> = 150°C	_ _	200 400	pA nA
N CHARACT	ERISTICS	•			
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current (Note 4)	V <sub>DS</sub> = 20 V, I <sub>GS</sub> = 0	8	_	mA
V <sub>DS</sub> (on)	Drain-Source On Voltage	I <sub>D</sub> = 2.5 mA, V <sub>GS</sub> = 0	-	0.2	V
r <sub>DS</sub> (on)	Drain-Source On Resistance	I <sub>D</sub> = 1 mA, V <sub>GS</sub> = 0	-	80	Ω
MALL SIGNA	AL CHARACTERISTICS	•			
r <sub>DS</sub> (on)	Drain-Source On Resistance	V <sub>DS</sub> = V <sub>GS</sub> = 0, f = 1 kHz	-	80	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz	-	16	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>DS</sub> = -20 V, f = 1.0 MHz	-	5	pF
WITCHING C	HARACTERISTICS				
t <sub>On</sub>	Turn-On Time	I <sub>D(on)</sub> = 3.0 mA	-	60	ns
t <sub>Off</sub>	Turn-Off Time	V <sub>GS(off)</sub> = 3.0 V	_	80	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>4.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  1%.

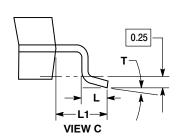


SOT-23 (TO-236) CASE 318-08 **ISSUE AS** 

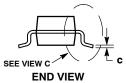
**DATE 30 JAN 2018** 

## SCALE 4:1 D - 3X b

**TOP VIEW** 







## **RECOMMENDED SOLDERING FOOTPRINT**



DIMENSIONS: MILLIMETERS

#### NOTES:

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
  MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.039	0.044	
A1	0.01	0.06	0.10	0.000	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.017	0.020	
С	0.08	0.14	0.20	0.003	0.006	0.008	
D	2.80	2.90	3.04	0.110	0.114	0.120	
E	1.20	1.30	1.40	0.047	0.051	0.055	
е	1.78	1.90	2.04	0.070	0.075	0.080	
L	0.30	0.43	0.55	0.012	0.017	0.022	
L1	0.35	0.54	0.69	0.014	0.021	0.027	
HE	2.10	2.40	2.64	0.083	0.094	0.104	
Т	0°		10°	0°		10°	

## **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	ı	
STYLE 9:	STYLE 10:	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN		PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE		2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE		3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE		PIN 1. NO CONNECTION	I PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE		2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE		3. ANODE	3. CATHODE-ANODE	5. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE				

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